To: Commissioner of Patents and Trademarks Washington, D.C. 20231

Fr: George O. Saile

Reg. No. 19,572

28 Davis Avenue

Poughkeepsie, N.Y. 12603

Subject:

Continuation of

Serial No.: 09/970,787 10/5/01

LAIN-JONG LI, TIEN-I BAO, SHWANG-MING JENG, SYUN-MING JANG, JUN-LUNG HUANG, JEN - CHENG

LIU

COMPOSITE ETCHING STOP IN SEMICONDUCTOR

PROCESS INTEGRATION

PRELIMINARY AMENDMENT

Dear Sir:

This is a preliminary amendment for the above referenced Continual Patent

Application. Please amend the above identified application for patent as follows:

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner of Patents and Trademarks, Washington, D.C. 20231, on April 13, 2004.

Stephen B. Ackerman, Reg. No. 37,761

Signature/Date

4/13/04

March 23, 2004

To: Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Fr: Stephen B. Ackerman, Reg. No. 37,761

28 Davis Avenue

Poughkeepsie, N.Y. 12603

Subject:

Serial No.

09/970,787

10/05/2001

L.J.LI ET AL

"COMPOSITE ETCHING STOP IN SEMICONDUCTOR PROCESS INTEGRATION"

PRELIMINARY AMENDMENT

Dear Sir:

Please enter a preliminary amendment for the divisional of the above-identified application for patent as follows:

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on 150, 2004.

Stephen B. Ackerman, Reg. No. 37,761

Signature

Date Dail 13,2004

Amendments to the Claims are reflected in the listing of the Claims which begins on page 3 of this paper.

Remarks/Arguments begin on page 8 of this paper.